- Single-Chip and Single-Supply Interface for IBM™ PC/AT™ Serial Port
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- Always-Active Noninverting Receiver Output (ROUT2B)
- Designed to Transmit at a Data Rate of 250 kbit/s
- Low Standby Current . . . 1 μA Typical
- External Capacitors . . . 4 × 0.1 μF
- Accepts 5-V Logic Input With 3.3-V Supply
- Designed to Be Interchangeable With Maxim MAX3243
- Serial-Mouse Driveability
- RS-232 Bus-Pin ESD Protection Exceeds ±15-kV Using Human-Body Model (HBM)†
- Applications
 - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages

 † Manual human-body model ESD testing performed on bus pins exceeds ± 15 kV. Current human-body model ESD testing capabilities per JESD 22, A114–A, is ± 8 kV. RS-232 bus pins on this device pass ± 8 kV.

(TOP VIEW) C2+ 28 C1+ C2- 2 27 V+ V-[]3 26 VCC RIN1 14 25 GND 24 C1-RIN2 5 RIN3 6 23 FORCEON 22 FORCEOFF RIN4 7 RIN5∏8 21 NVALID DOUT1 9 20 ROUT2B 19 ROUT1 DOUT2 10 DOUT3 I 11 18 ∏ ROUT2 DIN3 12 17 ROUT3 DIN2 13 16 ROUT4 15 ROUT5 DIN1 14

DB, DW, OR PW PACKAGE

description

The MAX3243 device consists of three line drivers, five line receivers, and a dual charge-pump circuit with ±15-kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. This combination of drivers and receivers matches that needed for the typical serial port used in an IBM PC/AT, or compatible. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT2B), which allows applications using the ring indicator to transmit data while the device is powered down. The device operates at data signaling rates up to 250 kbit/s and a maximum of 30-V/μs driver output slew rate.

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If FORCEOFF is set low, both drivers and receivers (except ROUT2B) are shut off, and the supply current is reduced to 1 μA. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur.

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3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

SLLS350C - APRIL 1999 - REVISED JUNE 2000

description (continued)

Auto-powerdown can be disabled when FORCEON and $\overline{FORCEOFF}$ are high, and should be done when driving a serial mouse. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The $\overline{INVALID}$ output is used to notify the user if an RS-232 signal is present at any receiver input. $\overline{INVALID}$ is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V or has been between -0.3 V and 0.3 V for less than 30 μ s. $\overline{INVALID}$ is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30 μ s. Refer to Figure 5 for receiver input levels.

The MAX3243C is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

	Р	ACKAGED DEVICES	
TA	SHRINK SMALL OUTLINE (DB)	SMALL OUTLINE (DW)	THIN SHRINK SMALL OUTLINE (PW)
0°C to 70°C	MAX3243CDB	MAX3243CDW	MAX3243CPW

The DB, DW, and PW packages are available taped and reeled. Add the suffix R to device type (e.g., MAX3243CDBR).

Function Tables

EACH DRIVER

		INPUTS		ОИТРИТ	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Χ	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
Н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

H = high level, L = low level, X = irrelevant, Z = high impedance

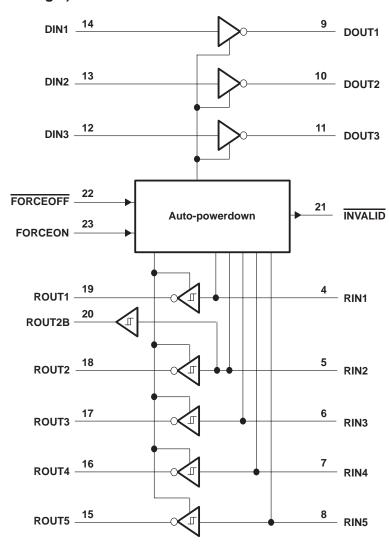
EACH RECEIVER

		INPUTS		OUTP	UTS	
RIN2	RIN1, RIN3–RIN5	FORCEOFF	VALID RIN RS-232 LEVEL	ROUT2B	ROUT	RECEIVER STATUS
L	Χ	L	Х	L	Z	Powered off while
Н	X	L	X	Н	Z	ROUT2B is active
L	L	Н	Yes	L	Н	
L	Н	Н	Yes	L	L	Normal operation with
Н	L	Н	Yes	Н	Н	auto-powerdown
Н	Н	Н	Yes	Н	L	disabled/enabled
Open	Open	Н	No	L	Н	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	0.3 V to 7 V
Negative output supply voltage range, V– (see Note 1)	0.3 V to –7 V
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V _I : Driver (FORCEOFF, FORCEON)	0.3 V to 6 V
Receiver	
Output voltage range, V _O : Driver	13.2 V to 13.2 V
Receiver (INVALID)	0.3 V to V_{CC} + 0.3 V
Package thermal impedance, θ _{JA} (see Note 2): DB package	62°C/W
DW package	
PW package	62°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

recommended operating conditions (see Note 3 and Figure 6)

				MIN	NOM	MAX	UNIT
	Supply voltage		V _{CC} = 3.3 V	3	3.3	3.6	V
			V _{CC} = 5 V	4.5	5	5.5	V
Maria	Driver and central high level input valtage	DIN FORGE FORGEON	V _{CC} = 3.3 V	2			V
VIH	Driver and control high-level input voltage	DIN, FORCEOFF, FORCEON	V _{CC} = 5 V	2.4			V
VIL	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON				0.8	V
٧ _I	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
٧ _I	/I Receiver input voltage			-25		25	V
T _A	Operating free-air temperature		MAX3243C	0		70	°C

NOTE 3: Test conditions are C1–C4 = 0.1 μ F at V $_{CC}$ = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V $_{CC}$ = 5 V \pm 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAME	TER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
ΙΙ	Input leakage current	FORCEOFF, FORCEON			±0.01	±1	μΑ
		Auto-powerdown disabled	No load, FORCEOFF and FORCEON at V _{CC}		0.3	1	mA
		Powered off	No load, FORCEOFF at GND		1	10	
Icc	Supply current	Auto-powerdown enabled	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded All DIN are grounded		1	10	μΑ

[‡] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 3. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



^{2.} The package thermal impedance is calculated in accordance with JESD 51.

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Vон	High-level output voltage	All DOUT at R _L = 3 k Ω to GND	5	5.4		V
VOL	Low-level output voltage	I DOUT at R _L = 3 k Ω to GND		-5.4		V
Vo	Output voltage (mouse driveability)	DIN1 = DIN2 = GND, DIN3 = V_{CC} , 3- $k\Omega$ to GND at DOUT3, DOUT1 = DOUT2 = 2.5 mA	±5			V
ΊΗ	High-level input current	$V_I = V_{CC}$		±0.01	±1	μΑ
Ι _Ι L	Low-level input current	V _I at GND		±0.01	±1	μΑ
la a	Object also the terminal	$V_{CC} = 3.6 \text{ V}, \qquad \qquad V_{O} = 0 \text{ V}$		±35	±60	mA
los	Short-circuit output current‡	$V_{CC} = 5.5 \text{ V}, \qquad \qquad V_{O} = 0 \text{ V}$		±33	±00	IIIA
r _O	Output resistance	V_{CC} , V+, and V- = 0 V, V_{O} = ± 2 V	300	10M		Ω
loff	Output leakage current	FORCEOFF = GND, $V_O = \pm 12 \text{ V}$, $V_{CC} = 0 \text{ to } 5.5 \text{ V}$			±25	μΑ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 3. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
	Maximum data rate	C _L = 1000 pF, One DOUT switching,	$R_L = 3 kΩ$, See Figure 1		250		kbit/s
tsk(p)	Pulse skew§	C _L = 150 pF to 2500 pF	R _L = 3 kΩ to 7 kΩ, See Figure 2		100		ns
SR(tr)	Slew rate, transition region	V _{CC} = 3.3 V,	C _L = 150 pF to 1000 pF	6		30	V/μs
SK(II)	(see Figure 1)	$R_L = 3 k\Omega$ to $7 k\Omega$	C _L = 150 pF to 2500 pF	4		30	ν/μ5

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

§ Pulse skew is defined as $|tp_{LH} - tp_{HL}|$ of each channel of the same device. NOTE 3. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 $V \pm 0.3 V$; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 $V \pm 0.5 V$.



^{\$} Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Vон	High-level output voltage	I _{OH} = -1 mA	V _{CC} – 0.6 V	V _{CC} – 0.1 V		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
\/	Positive-going input threshold voltage	V _{CC} = 3.3 V		1.6	2.4	V
VIT+	Positive-going input tilleshold voltage	V _{CC} = 5 V		1.9	2.4	٧
\/	Negative-going input threshold voltage	V _{CC} = 3.3 V	0.6	1.1		V
VIT-	Negative-going input timeshold voltage	V _{CC} = 5 V	0.8	1.4		٧
V _{hys}	Input hysteresis (V _{IT+} - V _{IT-})			0.5		V
l _{off}	Output leakage current (except ROUT2B)	FORCEOFF = 0 V		±0.05	±10	μΑ
rį	Input resistance	$V_1 = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 3. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3)

PARAMETER		TEST CONDITIONS	MIN TYPT MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	C _I = 150 pF, See Figure 3	150	ns
tPHL	Propagation delay time, high- to low-level output	CL = 150 pr, See Figure 3	150	ns
t _{en}	Output enable time	C: 450 pF D: 2 kO See Figure 4	200	ns
^t dis	Output disable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{See Figure 4}$	200	ns
t _{sk(p)}	Pulse skew [‡]	See Figure 3	50	ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 3. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.



[‡] Pulse skew is defined as |tplh - tphl| of each channel of the same device.

AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	түр† І	MAX	UNIT
VT+(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}			2.7	V
VT-(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-2.7			V
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-0.3		0.3	V
VOH	INVALID high-level output voltage	$I_{OH} = -1 \text{ mA}$, FORCEON = GND, FORCEOFF = V_{CC}	V _{CC} - 0.6			V
VOL	INVALID low-level output voltage	$I_{OL} = 1.6 \text{ mA}$, FORCEON = GND, FORCEOFF = V_{CC}			0.4	V

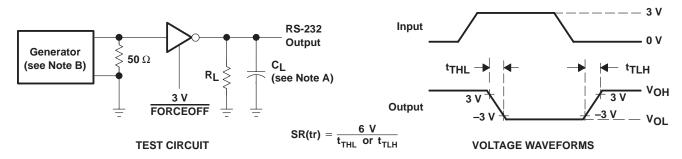
 $[\]dagger$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	MIN	TYP [†]	MAX	UNIT
^t valid	Propagation delay time, low- to high-level output		1		μs
^t invalid	Propagation delay time, high- to low-level output		30		μs
t _{en}	Supply enable time		100		μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION



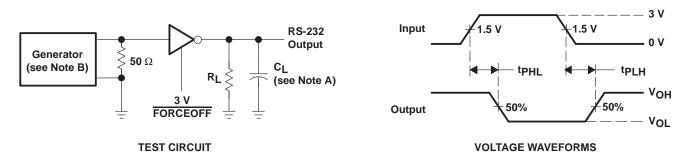
NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_\Gamma \le 10$ ns.

Figure 1. Driver Slew Rate



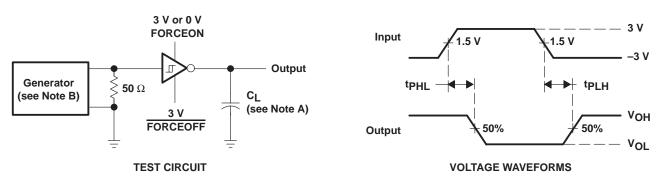
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

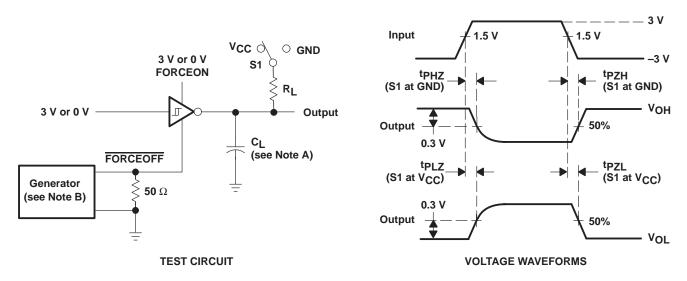
Figure 2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 3. Receiver Propagation Delay Times



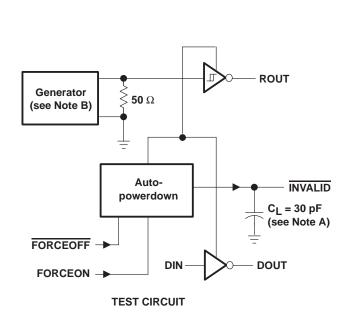
NOTES: A. C_L includes probe and jig capacitance.

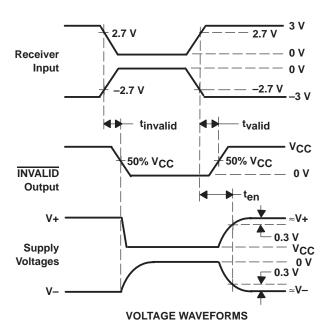
- B. The pulse generator has the following characteristics: $Z_O = 50~\Omega$, 50% duty cycle, $t_\Gamma \le 10~\text{ns}$, $t_f \le 10~\text{ns}$.
- C. tpLz and tpHz are the same as tdis.
- D. tpzL and tpzH are the same as ten.

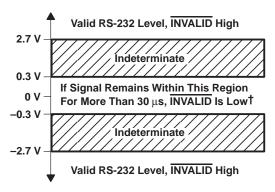
Figure 4. Receiver Enable and Disable Times



PARAMETER MEASUREMENT INFORMATION







† Auto-powerdown disables drivers and reduces supply current to 1 μA.

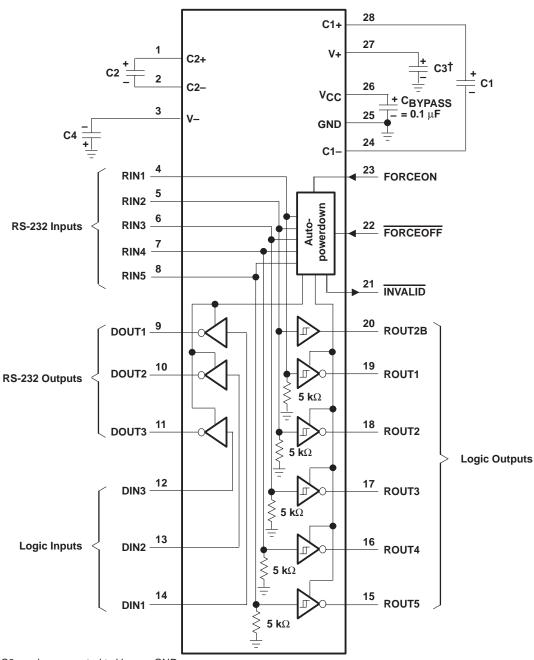
NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 5. INVALID Propagation Delay Times and Supply Enabling Time



APPLICATION INFORMATION



 † C3 can be connected to VCC or GND. NOTE A: Resistor values shown are nominal.

V_{CC} vs CAPACITOR VALUES

VCC	C1	C2, C3, and C4
$\begin{array}{c} 3.3 \text{ V} \pm 0.3 \text{ V} \\ 5 \text{ V} \pm 0.5 \text{ V} \\ 3 \text{ V to 5.5 V} \end{array}$	0.1 μF 0.047 μF 0.1 μF	0.1 μF 0.33 μF 0.47 μF

Figure 6. Typical Operating Circuit and Capacitor Values



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